

REJ03D0471–0200 Rev.2.00 Feb.18.2005

This 8-bit addressable latch is designed for general purpose storage applications in digital systems. Specific uses include working registers, serial-holding registers, and active-high decoders or demultiplexers. This is multifunctional device capable of storing single-line data in eight addressable latches, and being a 1-to-8 decoder or demultiplexer with active-high outputs.

Four distinct modes of operation are selectable by controlling the clear and enable inputs as enumerated in the function table. In the addressable-latch mode, data at the data-in terminal is written into the addressed latch.

The addressed latch will follow the data input with all unaddressed latches remaining in their previous states. In the memory mode, latch remains in their previous states and is unaffected by the data or address inputs.

To eliminate the possibility of entering erroneous data in the latch, the enable should be held high (inactive) while the address lines are changing.

In the clear mode, all outputs are low and unaffected by the address and data inputs.

### Features

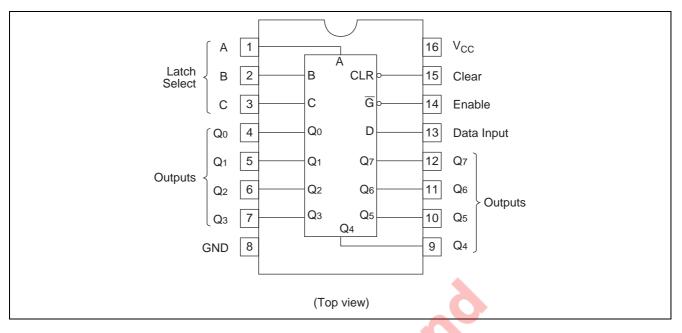
• Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS259P	DILP-16 pin	PRDP0016AE-B (DP-16FV)	_	_
HD74LS259FPEL	SOP-16 pin (JEITA)	PRSP0016DH-B (FP-16DAV)	FP	EL (2,000 pcs/reel)
HD74LS259RPEL	SOP-16 pin (JEDEC)	PRSP0016DG-A (FP-16DNV)	RP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.



## **Pin Arrangement**



## **Function Table**

Input		Output of	Each other output	Function	
CLR	G	addressed latch			
Н	L	D	Qio	Addressable latch	
Н	Н	Qio	Qio	Memory	
L	L	D	L	8-line demultiplexer	
L	Н	L	L	Clear	

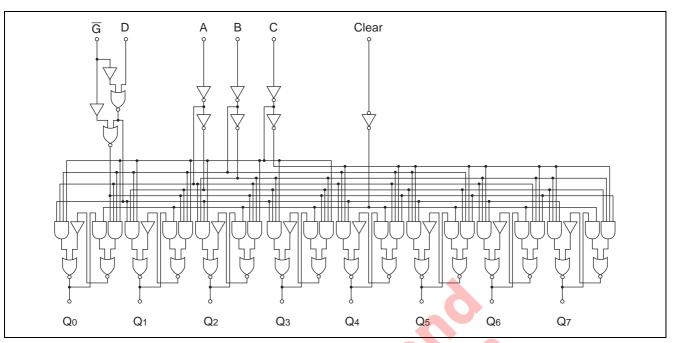
С	Select inputs B	Latch addressed	
L		L	0
L		Н	1
L	н	L	2
L	н	Н	3
н		L	4
Н	L	Н	5
Н	Н	L	6
Н	Н	Н	7

Notes: 1. H; high level, L; low level

2. D; the level at the data input

3.  $O_{io}$ ; the level of  $Q_i$  (i = 0, 1, ... 7, as appropriate) before the indicated steady state input conditions were established.

# **Block Diagram**



# **Absolute Maximum Ratings**

ltem	Symbol	Ratings	Unit	
Supply voltage	V <sub>cc</sub>	7	V	
Input voltage	V <sub>IN</sub>	7	V	
Power dissipation	PT	400	mW	
Storage temperature	Tstg	-65 to +150	°C	

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

# **Recommended Operating Conditions**

Item		Symbol	Min	Тур	Max	Unit
Supply voltage		V <sub>cc</sub>	4.75	5.00	5.25	V
Output current		Іон			-400	μΑ
Oulput current		I <sub>OL</sub>			8	mA
Operating temperature		Topr	-20	25	75	°C
Pulse width		t <sub>w</sub>	15	—	—	ns
Setup time	Data	t <sub>su</sub>	20↑			ns
	Address	t <sub>su</sub>	20↑	_	_	ns
Hold time	Data	t <sub>h</sub>	0↑			ns
	Address	t <sub>h</sub>	0↑			ns



## **Electrical Characteristics**

 $(Ta = -20 \text{ to } +75 \ ^{\circ}\text{C})$ 

Item	Symbol	min.	typ.*	max.	Unit	Condition		
Input voltage	V <sub>IH</sub>	2.0		—	V			
input voltage	V <sub>IL</sub>			0.8	V			
Output valtage	V <sub>он</sub>	2.7		_	V	$\label{eq:VCC} \begin{split} V_{CC} &= 4.75 \ \text{V}, \ V_{\text{IH}} = 2 \ \text{V}, \ V_{\text{IL}} = 0.8 \ \text{V}, \\ I_{OH} &= -400 \ \mu\text{A} \end{split}$		
Output voltage	V <sub>OL</sub>			0.4	V	$I_{OL} = 4 \text{ mA}$ $V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V},$		
				0.5	v	I <sub>OL</sub> = 8 mA V <sub>IL</sub> = 0.8 V		
	I <sub>IH</sub>			20	μA	$V_{CC} = 5.25 \text{ V}, \text{ V}_{I} = 2.7 \text{ V}$		
Input current	IIL			-0.4	mA	$V_{CC} = 5.25 \text{ V}, \text{ V}_{I} = 0.4 \text{ V}$		
	II.			0.1	mA	$V_{CC} = 5.25 \text{ V}, \text{ V}_{I} = 7 \text{ V}$		
Short-circuit output current	los	-20	_	-100	mA	V <sub>CC</sub> = 5.25 V		
Supply current**	Icc		22	36	mA	V <sub>CC</sub> = 5.25 V		
Input clamp voltage	VIK	_	_	-1.5	V	$V_{CC} = 4.75 \text{ V}, I_{IN} = -18 \text{ mA}$		

Notes: \*  $V_{CC} = 5 V$ , Ta = 25°C

\*\* I<sub>CC</sub> is measured with all outputs open and all inputs grounded.

# **Switching Characteristics**

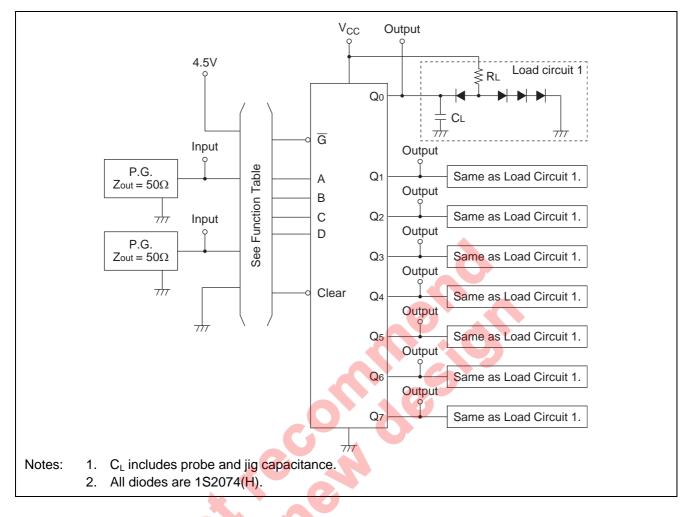
				(	0		$(V_{CC} = 5)$	V, Ta = 25°C)
ltem	Symbol	Inputs	Output	min.	typ.	max.	Unit	Condition
	t <sub>PHL</sub>	Clear	$Q_0$ to $Q_7$		17	27	ns	
	t <sub>PLH</sub>	Data	$Q_0$ to $Q_7$		20	32	ns	- C <sub>L</sub> = 15 pF, R <sub>L</sub> = 2 kΩ
	t <sub>PHL</sub>			-	13	21		
Propagation delay time	t <sub>PLH</sub>	Address	Q <sub>0</sub> to Q <sub>7</sub>	-	24	38	ns	
	t <sub>PHL</sub>				18	29		
	t <sub>PLH</sub>	Frabla	Q <sub>0</sub> to Q <sub>7</sub>		22	35	ns	
	t <sub>PHL</sub>	Enable		—	15	24		



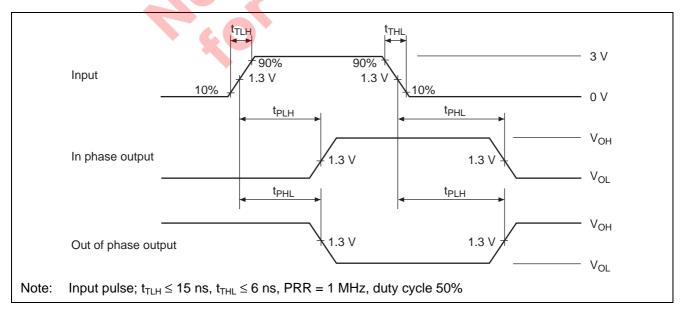


# **Testing Method**

### **Test Circuit**

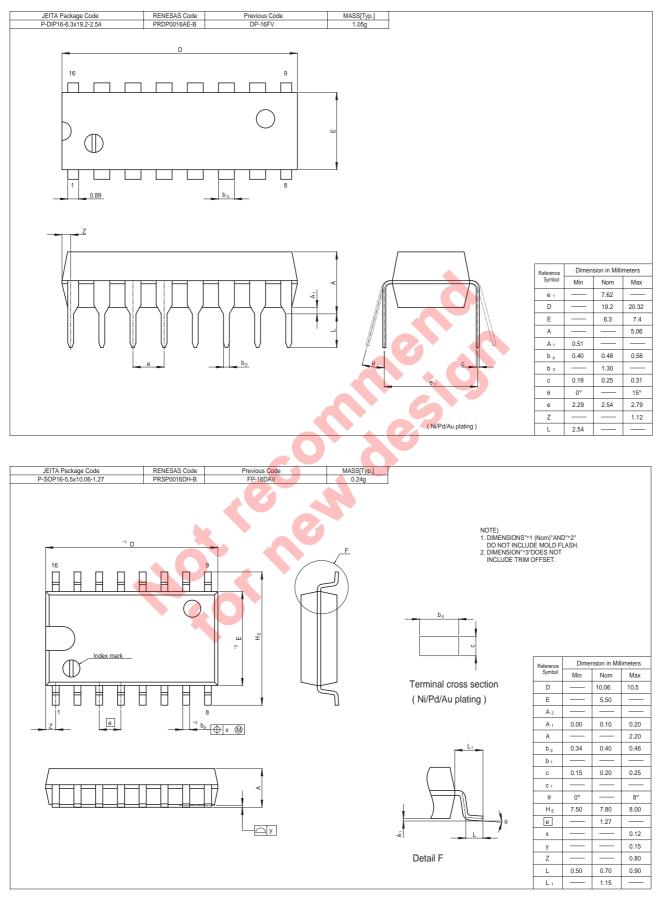


### Waveform



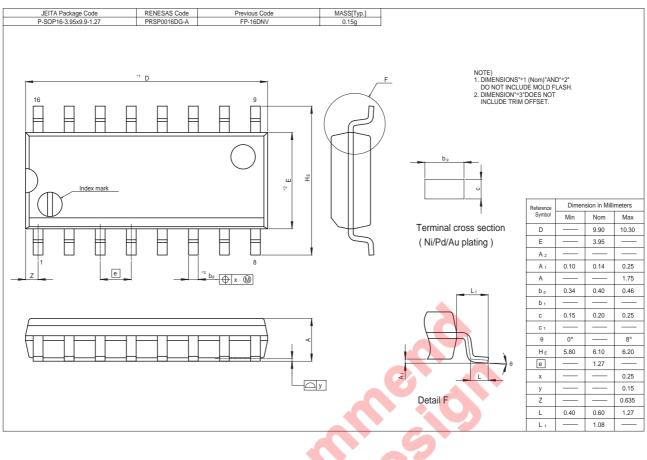


## **Package Dimensions**





### HD74LS259





# Renesas Technology Corp. Sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Keep safety first in your circuit designs! 1. Renesas Technology Corp. puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

- (ii) Use of nonnammapie material of (iii) prevention against any marunction of misnap.
  Notes regarding these materials are intended as a reference to assist our customers in the selection of the Renesas Technology Corp. product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Renesas Technology Corp. or a third party.
  Renesas Technology Corp. assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
  All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Renesas Technology Corp. without notice due to product improvements or other reasons. It is therefore recommended that customers contain technical inaccuracies or typographical errors. Renesas Technology Corp. assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors. Please also pay attention to information published by Renesas Technology Corp. by various means, including the Renesas Technology Corp. Semiconductor home page (http://www.renesas.com).
  When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Renesas Technology Corp. assumes no responsibility for any damage, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Renesas Technology Corp. assum

- use. 6. The prior written approval of Renesas Technology Corp. is necessary to reprint or reproduce in whole or in part these materials. 7. If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination. Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited. 8. Please contact Renesas Technology Corp. for further details on these materials or the products contained therein.



### **RENESAS SALES OFFICES**

Refer to "http://www.renesas.com/en/network" for the latest and detailed information.

Renesas Technology America, Inc. 450 Holger Way, San Jose, CA 95134-1368, U.S.A Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K. Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology Hong Kong Ltd. 7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd. 10th Floor, No.99, Fushing North Road, Taipei, Taiwan Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology (Shanghai) Co., Ltd. Unit2607 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd. 1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001

http://www.renesas.com